

RELIABILITY REPORT





NOW PART OF



Reliability Data Report

Product Family R567

LTC2933 \ LTC2936 \ LTC2937 \ LTC2943 \ LTC2944 \ LTC2945 \
LTC2947 \ LTC2949 \ LTC2955 \ LTC2960

Reliability Data Report

Report Number: R567

Report generated on: Fri Apr 10 18:04:23 PDT 2020

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C)¹	No. of FAILURES _{2, 3}
SSOP/TSSOP	460	1136	1412	460	0
QFN/DFN	1736	1146	1542	2045	0
Totals	2,196	-	-	2,505	0
HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C)⁴	No. of FAILURES
QFN/DFN	462	1445	1521	1774	0
Totals	462	-	-	1,774	0
PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	1634	1317	1637	303	0
SOIC/MSOP	398	1639	1710	9	0
SOT	1794	1312	1649	43	0
Totals	3,826	-	-	355	0
TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	1448	1317	1637	837	0
SOIC/MSOP	396	1639	1710	39	0
SOT	1794	1312	1649	179	0
Totals	3,638	-	-	1,055	0
THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	1158	1317	1637	709	0
SSOP/TSSOP	452	0924	1044	300	0
SOIC/MSOP	400	1639	1710	40	0
SOT	1786	1312	1649	178	0
Totals	3,796	-	-	1,227	0
<p>(1) Assumes Activation Energy = 0.7 Electron Volts (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =4.73 FITS (3) Mean Time Between Failure in Years = 24133.47 (4) Assumes 20X Acceleration from 85 °C to +130 °C Note 1: 1 FIT = 1 Failure in One Billion Hours. Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning</p>					

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HIGH TEMPERATURE BAKE AT 125 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	100	1615	1615	4	0
Totals	100	-	-	4	0
HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	1006	1236	1615	856	0
Totals	1,006	-	-	856	0
HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	286	1236	1542	186	0
SOIC/MSOP	200	1640	1710	100	0
SOT	100	1515	1515	50	0
Totals	586	-	-	336	0